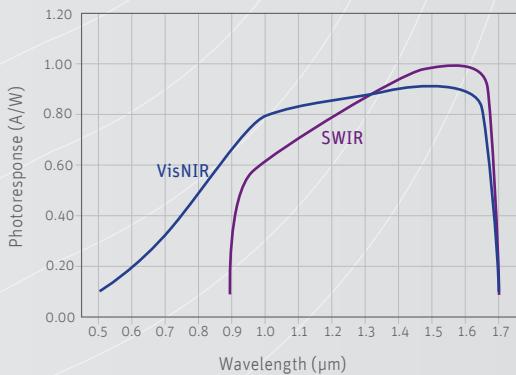


Imagine the invisible

Modules & components



XSW-640

High resolution
TE1-stabilized SWIR OEM module

Ready-to-integrate
SWIR OEM module
consuming ultra-low-power

Xenics' XSW-640 OEM module is extremely compact and versatile for easy and swift integration in your SWIR imaging configuration.

Typical OEM applications include infrared imaging for man-portable and unmanned (airborne and land-based) vehicle payloads, night vision, border security, Search & Rescue (SAR) and more.

The XSW-640 OEM module detects short wave infrared radiation between 0.9 (optionally 0.4) and 1.7 μm with a wide dynamic range and wide operating temperature.

The Thermo Electric (TE) stabilization reduces the dark current and noise levels. Together with on-board image processing you will have best contrast and high image quality.

Designed for use in



Person identification

Camouflage detection

Vision enhancement: looking through haze with SWIR

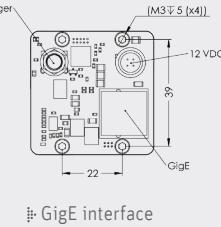
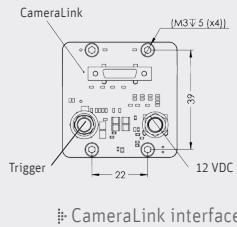
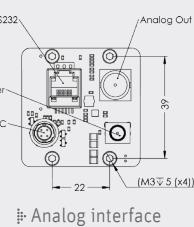
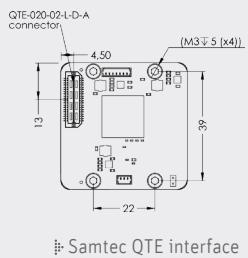
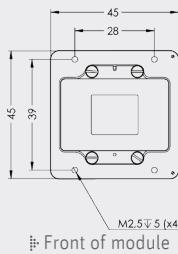
Key features

- Made in Europe
- High resolution
- Easy connectivity
- Small 20 μm pixel pitch

OEM applications

- SWIR sights
- UAV / UGV
- Border security
- Laser detection
- Night vision (passive & active)
- Search & Rescue
- Driver assistance
- Electro optical payloads
- Long range identification
- Enhanced Vision Systems (EVS)

Ready-to-integrate



Specifications

Module specifications	XSW-640-Samtec	XSW-640-Analog	XSW-640-CL	XSW-640-GigE		
Lens						
Focal length	Broad range of lenses optional available					
Optical interface	Fixation holes for multiple lens mount					
Imaging performance						
Frame rate	Max 100 Hz	25 Hz (PAL) 30 Hz (NTSC)	Max 100 Hz			
Window of Interest	Minimum size 32 x 4					
Exposure time range	1 µs - 40 ms in high gain mode					
Noise*	High gain: 120 e- Low gain: 400 e-					
Gain	High gain mode: 1.28 e-/ADU Low gain mode: 16.2 e-/ADU					
On-board image processing	Image correction (TrueNUC for high gain and low gain), auto gain, auto exposure, histogram equalization, trigger possibilities		Up to 4 NUCs, auto gain, trigger possibilities			
ADC	14 bit					
Interfaces						
Digital output	BT.601-6/ BT.656-5	-	CameraLink or Xeneth API/ SDK	GigE Vision or Xeneth API/SDK		
Analog output	-	PAL or NTSC	-	-		
Module control	Serial LVC MOS 3 V (XSP)	RS232 (XSP)	CameraLink	GigE Vision		
Trigger	In or out (configurable)					
Power requirements						
Power consumption* (without TEC)	2.5 W	3 W	2.8 W	4 W		
Power supply	+/- 12 V					
Physical characteristics						
Shock	40 G, 11 ms halfsine profile, according to MIL-STD810G					
Vibration	5 G, (20 Hz to 1000 Hz), according to MIL-STD883J					
Operating case temperature	-40 °C to 70 °C (industrial components)					
Storage temperature	-45 °C to 85 °C (industrial components)					
Dimensions (W x H x L mm ³)	45 x 45 x 51	45 x 45 x 55	45 x 45 x 55	55 x 55 x 65		
Weight module (without lens)	120 g	145 g	129 g	165 g		

* Typical values

Array specifications	XSW-640
Sensor type	InGaAs Focal Plane Array (FPA) ROIC with CTIA** topology
Spectral band	0.9 to 1.7 µm Optional 0.4 to 1.7 µm (VisNIR)
# pixels	640 x 512
Pixel pitch	20 µm
Readout mode	Integrate Then Read (ITR) Integrate While Read (IWR)
Quantum efficiency	80 % @ 1.6 µm (SWIR) 85 % @ 0.9 µm (VisNIR)
ROIC noise*	High gain: 60 e-; low gain: 400 e-
Sensitivity*	High gain: 20 pV/e-; low gain: 1.6 pV/e-
Dark current*	0.8 x 10 ⁶ e-/s
Integration capacitor	High gain: 6.7 fF; low gain: 85 fF
Array cooling	TE1-stabilized
Pixel operability	> 99 %

* Typical values

** Capacitor TransImpedance Amplifier

Product selector guide

Part number	Frame rate	Interface	VisNIR
XEN-000295*		16bitDV	
XEN-000304**	100 Hz	BT.656	No
XEN-000343		CameraLink	
XEN-000341		GigE Vision	
XEN-000347	25 Hz	PAL	
XEN-000348	30 Hz	NTSC	
XEN-000098*		16bitDV	
XEN-000305**	100 Hz	BT.656	Yes
XEN-000344		CameraLink	
XEN-000342		GigE Vision	
XEN-000349	25 Hz	PAL	
XEN-000350	30 Hz	NTSC	
Part number	Interface	Connects with	Optional
ASY-000880*	CameraLink	XEN-000295 XEN-000098	Yes
ASY-000879**	PAL/NTSC	XEN-000304 XEN-000305	

* and ** Optional test board interface